# **Supporting Information**

# Ultra-low thermal conductivity in $B_2O_3$ composited SiGe bulk with

## enhanced thermoelectric performance at medium temperature region

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#### 1. The Lorentz calculation

Because the charge carriers transport both heat and charge,  $\kappa_e$  is commonly estimated using the measured  $\sigma$  by the Wiedemann-Franz law:  $\kappa_e = L\sigma T$ , where L is the Lorenz number. Once  $\kappa_e$  is known,  $\kappa_l$  is computed by subtracting the  $\kappa_e$  from the total thermal conductivity,  $\kappa = \kappa_e + \kappa_l$ .

For a single parabolic band, L and S are both functions of reduced chemical potential ( $\eta$ ) and carrier scattering factor ( $\lambda$ ) only, the value of L is calculated according to the following formula:

$$L = \left(\frac{k_B}{e}\right)^2 \frac{(1+\lambda)(3+\lambda)F_{\lambda}(\eta)F_{\lambda+2}(\eta) - (2+\lambda)^2F_{\lambda+1}(\eta)^2}{(1+\lambda)^2F_{\lambda}(\eta)^2}$$
$$S = \frac{k_B}{e} \left(\frac{(2+\lambda)F_{\lambda+1}(\eta)}{(1+\lambda)F_{\lambda}(\eta)} - \eta\right)$$

Where  $F_i(\eta)$  represents the Fermi integral,

$$F_{j}(\eta) = \int_{0}^{\infty} \frac{\epsilon^{j} d ! \epsilon}{1 + Exp[\epsilon - \eta]}$$

The Lorentz calculation values of different B<sub>2</sub>O<sub>3</sub> adding amounts are shown in Fig. S1.



Fig. S1 Lorentz calculated value.

#### 2. Effect of B<sub>2</sub>O<sub>3</sub> on crystallization

In the miantext, it can be seen from XRD pattern, the stronger peaks intensities with the increase of the  $B_2O_3$  content indicate that adding of  $B_2O_3$  promotes the crystallization of SiGe. In addition to XRD characterization, we prepared samples without and added with  $B_2O_3$  with the same sintering method and sintering time, and then characterized by SEM. As shown in Fig. S1(a), many holes and poor compactness in the sample without  $B_2O_3$  are disclosed under the premise of the same preparation process. Figure S1(b) shows the sample added with  $B_2O_3$ , which has good porosity and compactness, further illustrating that  $B_2O_3$  can promote crystallization.



Fig. S2 (a) The SEM images of the sample without B<sub>2</sub>O<sub>3</sub>, (b) the SEM images of the sample added with B<sub>2</sub>O<sub>3</sub>

#### 3. The EPMA measurement

EPMA works by bombarding micro-volume samples with focused electron beams and collecting Xrays emitted by various elements. Since the wavelengths of X-rays are characteristic of the emitting material, the sample components can be easily identified by recording wavelength dispersion spectra.

Figure. S3 is the EPMA test of  $Si_{80}Ge_{20}B_{1.5}(B_2O_3)_{0.6}$  sample. It can be seen from the figure that the composition of point 1 and point 2 is different, and it can be judged that there are two phases. In addition, the sample was tested by surface scanning, and it was found that B element was distributed sporadically. It was inferred that it was probably a nano-second-phase containing  $B_2O_3$ , which needed to be further confirmed by TEM analysis.



Fig. S3 The EPMA measurement of  $Si_{80}Ge_{20}B_{1.5}(B_2O_3)_{0.6}$  Sample

## 4. The TEM observation

We have carried out TEM analysis in other different areas, and we can also find micropores, nanosecond-phase, it is proved from the side that the micropores and the nano-second-phase are uniformly distributed.



Fig. S4 TEM image of the micropores and nano-second-phase.

### 5. Fitting calculation of lattice thermal conductivity

We use the Callaway model to calculate the lattice thermal conductivity,<sup>1-3</sup> and the details are as follows.

$$k_{l} = \frac{k_{B}}{2\pi^{2}\nu} \left(\frac{k_{B}T}{\hbar}\right)^{3} \int_{0}^{\theta_{D}/T} \frac{x^{4}e^{x}}{\tau_{C}^{-1}(e^{x}-1)^{2}} dx$$

where  $x = \hbar \omega / (kBT)$ , kB,  $\omega$ ,  $\hbar$ ,  $\theta D$ ,  $\nu$  and  $\tau_c^{-1}$  are the reduced phonon frequency, Boltzmann constant, phonon frequency, reduced Planck constant, Debye temperature, sound velocity and phonon-scattering relaxation time, respectively.

The relaxation time is affected by point defect scattering, phonon-phonon scattering, stacking fault and electron-phonon scattering, second phase, micropore and grain boundary scattering, as shown in the following formula.

$$\tau_c^{-1} = A\omega^4 + B\omega^2 T \exp\left(-\theta_D / 3T\right) + C\omega^2 + \frac{\nu}{d}$$

Among them,  $A\omega^4$  corresponds to the relaxation time of the scattering of point defects, relaxation time of phonon-phonon scattering corresponding to  $B\omega^2 T \exp(-\theta_D / 3T)$ ,  $C\omega^2$  corresponds to the  $\nu$ 

relaxation time of the stacking fault and electron-phonon scattering,  $\overline{d}$  corresponds to the relaxation time of the second phase, micropore and grain boundary scattering.

Combined with the actual test results and literature values,<sup>4-8</sup> we get the parameters of the following table. The d is obtained from the grain size distribution and micropore size distribution of TEM images, and the B is obtained by fitting with  $k_l$  known in previous studies. The point defect scattering is not considered, but only phonon-phonon scattering, electron-phonon scattering and boundary scattering are considered, by fitting the experimental  $k_l$ , C can be obtained when B is determined. On the premise that both B, C and d are determined, combined with the actual test results, A is calculated.

Table S1				
Composition	A(s <sup>3</sup> )	B(s/K)	C(s)	$\frac{\nu}{d}$ (s <sup>-1</sup> )
Si <sub>80</sub> Ge <sub>20</sub> B <sub>1.5</sub> (B <sub>2</sub> O <sub>3</sub> ) <sub>0.6</sub>	3500×10 <sup>-45</sup>	37×10 <sup>-20</sup>	0.4×10 <sup>-17</sup>	8×10 <sup>9</sup>

### References

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